

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE				ATTY. DOCKET NO.	SERIAL NO.		
FORM PTO-1449 (REV. 7-80)				TI-37133	TBD 10/691843		
LIST OF DOCUMENTS CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT Chen et al.			
				FILING DATE Herewith 10/23/03	GROUP 2813	TBD	
U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
<i>pm</i>		US 2002/0063292 A1	05/30/02	Armstrong et al.	257	367	11/29/00
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION
							YES NO
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
<i>0517</i>		"Silicon Processing for the VLSI Era," Stanley Wolf, Volume 4: Deep-Submicron Process Technology, 2002, pg. 446-452					
		"Choices & Challenges for Shallow Trench Isolation" Laura Peters, Semiconductor International, April, 1999, pg. 69-76					
		"Novel Corner Rounding Process for Shallow Trench Isolation utilizing MSTS (Micro-Structure Transformation of Silicon)" Matsuda et al, IEEE 1998, pg. 137-140					
EXAMINER <i>DS</i>				DATE CONSIDERED <i>2/28/03</i>			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

FORM PTO-1449 (REV. 7-80)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. TI-37133		SERIAL NO. 10/691,843	
LIST OF DOCUMENTS CITED BY APPLICANT <i>(Use several sheets if necessary)</i>							
<i>O I P E S C I S</i> <i>JUL 3 0 2004</i>				APPLICANT: Chen et al.			
				FILING DATE 10/23/2003		GROUP 2813	
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*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)	
DSR	6,150,234	11/21/00	Olsen	438	424	—	
	US 6,653,200 B2	11/25/03	Olsen	438	424	—	
	US 2003/0003759 A1	01/02/03	Kudelka	438	733	—	
	US 6,566,273 B2	05/20/03	Kudelka	438	733	—	
	US 2001/0038113 A1	11/08/01	Bronner et al.	257	301	—	
	US 6,426,251 B2	07/30/02	Bronner et al.	438	242	—	
	US 6,482,718 B2	11/19/02	Shiozawa	438	446	—	
	US 6,284,625 B1	09/04/01	Ishisuka et al.	438	425	—	
	US 6,649,489 B1	11/18/03	Chang et al.	438	424	—	
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	6,074,932	06/13/00	Wu	438	435	—	
	6,020,230	02/01/00	Wu	438	222	—	
	5,393,692	02/28/95	Wu	437	69	—	
	5,658,822	08/19/97	Wu et al.	438	446	—	
	US 6,482,715 B2	11/19/02	Park et al.	438	424	—	
	US 6,566,207 B2	05/20/03	Park	438	296	—	
	5,885,883	03/23/99	Park et al.	438	435	—	
	4,986,879	01/22/91	Lee	156	649	—	
	5,248,350	09/28/93	Lee	148	33.2	—	
	US 6,649,488 B2	11/18/03	Lee et al.	438	424	—	
	5,637,529	06/10/97	Jang et al.	437	69	—	
	5,910,018	06/08/99	Jang	438	425	—	
	5,940,719	08/17/99	Jang et al.	438	443	—	
	6,027,985	02/22/00	Jang et al.	438	443	—	
	5,849,626	12/15/98	Song	438	444	—	
FOREIGN PATENT DOCUMENTS							
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SU B CL AS S	TRANSLATION	
						YES	NO
OTHER DOCUMENTS <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i>							
EXAMINER	<i>DSR</i>			DATE CONSIDERED <i>2/28/05</i>			

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